

Phase Control Thyristors (Hockey PUK Version), 650 A



TO-200AC (B-PUK)

PRODUCT SUMMARY						
Package	TO-200AC (B-PUK)					
Diode variation	Single SCR					
I _{T(AV)}	650 A					
V _{DRM} /V _{RRM}	400 V, 800 V, 1200 V, 1400 V, 1600 V					
V _{TM}	1.90 V					
I _{GT}	100 mA					
T _J	-40 °C to 125 °C					

FEATURES

- · Center amplifying gate
- Metal case with ceramic insulator
- International standard case TO-200AC (B-PUK)



- High profile hockey PUK
- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

TYPICAL APPLICATIONS

- DC motor controls
- Controlled DC power supplies
- AC controllers

MAJOR RATINGS AND CHARACTERISTICS						
PARAMETER	METER TEST CONDITIONS VALUES		UNITS			
1		650	А			
I _{T(AV)}	T _{hs}	55	°C			
1		1230	A			
I _{T(RMS)}	T _{hs}	25	°C			
1	50 Hz	9000	Α Α			
I _{TSM}	60 Hz	9420	A			
² t	50 Hz	405	kA ² s			
	60 Hz	370	KA-S			
V _{DRM} /V _{RRM}		400 to 1600	V			
tq	Typical	100	μs			
T _J		-40 to +125	°C			

ELECTRICAL SPECIFICATIONS

VOLTAGE F	VOLTAGE RATINGS									
TYPE NUMBER	VOLTAGE CODE	V _{DRM} /V _{RRM} , MAXIMUM REPETITIVE PEAK AND OFF-STATE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK VOLTAGE V	I_{DRM}/I_{RRM} MAXIMUM AT $T_J = T_J$ MAXIMUM mA						
	04	400	500							
	08	800	900							
VS-ST330CL	12	1200	1300	50						
	14	1400	1500							
	16	1600	1700							



PARAMETER	SYMBOL		TEST CON	IDITIONS	VALUES	UNITS
Maximum average on-state current		180° condu	180° conduction, half sine wave		650 (314)	Α
at heatsink temperature	I _{T(AV)}	double side	double side (single side) cooled			°C
Maximum RMS on-state current	I _{T(RMS)}	DC at 25 °C	heatsink tempe	erature double side cooled	1230	
		t = 10 ms	No voltage		9000	
Maximum peak, one-cycle		t = 8.3 ms	reapplied		9420	Α
non-repetitive surge current	I _{TSM}	t = 10 ms	100 % V _{RRM}		7570	kA ² s
		t = 8.3 ms	reapplied	Sinusoidal half wave,	7920	
		t = 10 ms No v	No voltage reapplied	initial $T_J = T_J$ maximum	405	
Marrian and 12t fact frame	l ² t	t = 8.3 ms			370	
Maximum I ² t for fusing		t = 10 ms	100 % V _{RRM}		287	
		t = 8.3 ms	reapplied		262	
Maximum I ² √t for fusing	I²√t	t = 0.1 to 10	ms, no voltage	reapplied	4050	kA²√s
Low level value of threshold voltage	V _{T(TO)1}	(16.7 % x π	$x I_{T(AV)} < I < \pi x$	$I_{T(AV)}$), $T_J = T_J$ maximum	0.91	V
High level value of threshold voltage	V _{T(TO)2}	$(I > \pi \times I_{T(AV)})$	$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ maximum}$			V
Low level value of on-state slope resistance	r _{t1}	(16.7 % x π	(16.7 % x π x $I_{T(AV)}$ < I < π x $I_{T(AV)}$), $T_J = T_J$ maximum			mΩ
High level value of on-state slope resistance	r _{t2}	$(I > \pi \times I_{T(AV)}), T_J = T_J \text{ maximum}$			0.57	1115.2
Maximum on-state voltage	V_{TM}	$I_{pk} = 1730 \text{ A}, T_J = T_J \text{ maximum}, t_p = 10 \text{ ms sine pulse}$			1.90	V
Maximum holding current	I _H	T _ 05 °C	anada aupply 1	2 V registive lead	600	mΛ
Typical latching current	ΙL	1 J = 25 °C,	anoue supply 1	2 V resistive load	1000	mA

SWITCHING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum non-repetitive rate of rise of turned-on current	dl/dt	Gate drive 20 V, 20 Ω , $t_r \le 1~\mu s$ $T_J = T_J$ maximum, anode voltage $\le 80~\%~V_{DRM}$	1000	A/µs
Typical delay time	t _d	Gate current 1 A, $dl_g/dt = 1 A/\mu s$ $V_d = 0.67 \% V_{DRM}, T_J = 25 °C$	1.0	
Typical turn-off time	t _q	I_{TM} = 550 A, T_J = T_J maximum, dl/dt = 40 A/μs, V_R = 50 V, dV/dt = 20 V/μs, gate 0 V 100 Ω , t_p = 500 μs	100	μs

BLOCKING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = T_J$ maximum linear to 80 % rated V_{DRM}	500	V/µs
Maximum peak reverse and off-state leakage current	I _{RRM} , I _{DRM}	$T_J = T_J$ maximum, rated V_{DRM}/V_{RRM} applied	50	mA



TRIGGERING						
PARAMETER	SYMBOL	TEST CONDITIONS			VALUES	
PANAMETEN	STIMBOL	TES	TEST CONDITIONS			
Maximum peak gate power	P_{GM}	$T_J = T_J$ maximum,	t _p ≤ 5 ms	10	0.0	W
Maximum average gate power	P _{G(AV)}	$T_J = T_J$ maximum,	f = 50 Hz, d% = 50	2	.0	VV
Maximum peak positive gate current	I _{GM}	$T_J = T_J$ maximum,	t _p ≤ 5 ms	3	.0	Α
Maximum peak positive gate voltage	+V _{GM}	T. – T. maximum	t < 5 ms	2	<u>:</u> 0	V
Maximum peak negative gate voltage	-V _{GM}	ij = ij maximum,	$T_J = T_J$ maximum, $t_p \le 5$ ms			\ \ \
		T _J = -40 °C		200	-	
DC gate current required to trigger	I _{GT}	T _J = 25 °C	Maximum required gate trigger/ current/voltage are the lowest value which will trigger all units	100	200	mA
		T _J = 125 °C		50	-	
		T _J = -40 °C		2.5	-	
DC gate voltage required to trigger	V_{GT}	T _J = 25 °C	- 12 V anode to cathode applied		3.0	V
		T _J = 125 °C		1.1	-	
DC gate current not to trigger	I _{GD}	T T manyimay	Maximum gate current/voltage not to trigger is the maximum	10		mA
DC gate voltage not to trigger	V _{GD}	$T_J = T_J$ maximum	value which will not trigger any unit with rated V _{DRM} anode to cathode applied	0.	25	V

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum operating junction temperature range	$T_{\rm J}$		-40 to +125	°C		
Maximum storage temperature range	T _{Stg}		-40 to +150	C		
Maximum thermal resistance, junction to heatsink	_	DC operation single side cooled	0.11			
Maximum thermal resistance, junction to heatsink	R _{thJ-hs}	DC operation double side cooled	0.06	K/W		
Maximum thermal resistance, case to heatsink	D	DC operation single side cooled	0.011	IV VV		
Maximum thermal resistance, case to heatslink	R_{thC-hs}	DC operation double side cooled	0.005			
Mounting force, ± 10 %			9800 (1000)	N (kg)		
Approximate weight			250	g		
Case style		See dimensions - link at the end of datasheet	TO-200AC (B-PUK)		

△R _{thJ-hs} CONDUCTION								
CONDUCTION ANGLE	SINUSOIDAL		RECTANGULAR	RECTANGULAR CONDUCTION		UNITS		
CONDUCTION ANGLE	SINGLE SIDE	DOUBLE SIDE	SINGLE SIDE	DOUBLE SIDE	TEST CONDITIONS	UNITS		
180°	0.012	0.010	0.008	0.008				
120°	0.014	0.015	0.014	0.014				
90°	0.018	0.018	0.019	0.019	$T_J = T_J$ maximum	K/W		
60°	0.026	0.027	0.027	0.028				
30°	0.045	0.046	0.046	0.046				

Note

• The table above shows the increment of thermal resistance R_{thJ-hs} when devices operate at different conduction angles than DC



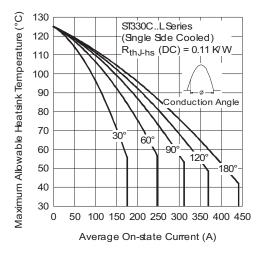


Fig. 1 - Current Ratings Characteristics

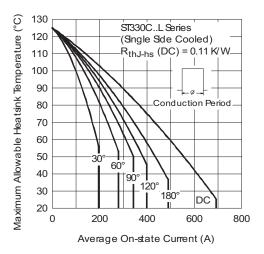


Fig. 2 - Current Ratings Characteristics

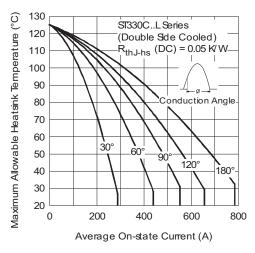


Fig. 3 - Current Ratings Characteristics

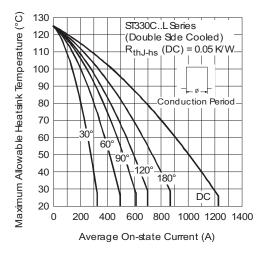


Fig. 4 - Current Ratings Characteristics

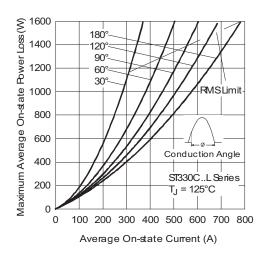


Fig. 5 - On-State Power Loss Characteristics

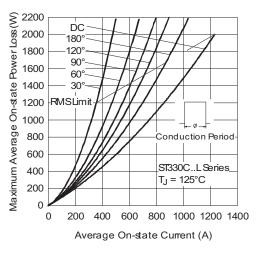


Fig. 6 - On-State Power Loss Characteristics

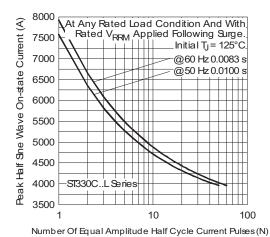


Fig. 7 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

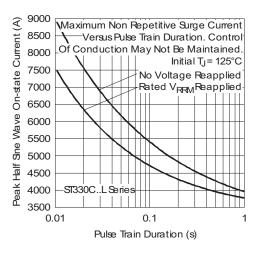


Fig. 8 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

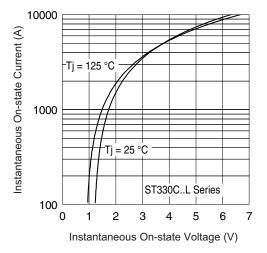


Fig. 9 - On-State Voltage Drop Characteristics

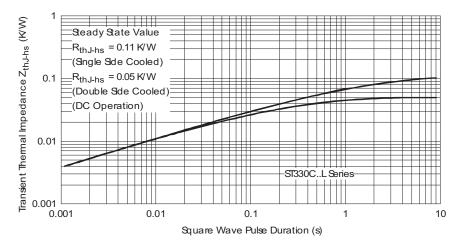


Fig. 10 - Thermal Impedance Z_{thJ-hs} Characteristics

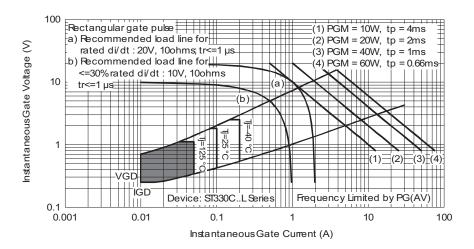


Fig. 11 - Gate Characteristics

ORDERING INFORMATION TABLE

Device code	VS-	ST	33	0	С	16	L	1	-
	1	2	3	4	5	6	7	8	9

Vishay Semiconductors product

2 - Thyristor

3 - Essential part number

4 - 0 = converter grade

5 - C = ceramic PUK

6 - Voltage code x 100 = V_{RRM} (see Voltage Ratings table)

7 - L = PUK case TO-200AC (B-PUK)

8 - 0 = eyelet terminals (gate and auxiliary cathode unsoldered leads)

1 = fast-on terminals (gate and auxiliary cathode unsoldered leads)

2 = eyelet terminals (gate and auxiliary cathode soldered leads)

3 = fast-on terminals (gate and auxiliary cathode soldered leads)

9 - Critical dV/dt: • None = 500 V/µs (standard selection)

• L = 1000 V/µs (special selection)

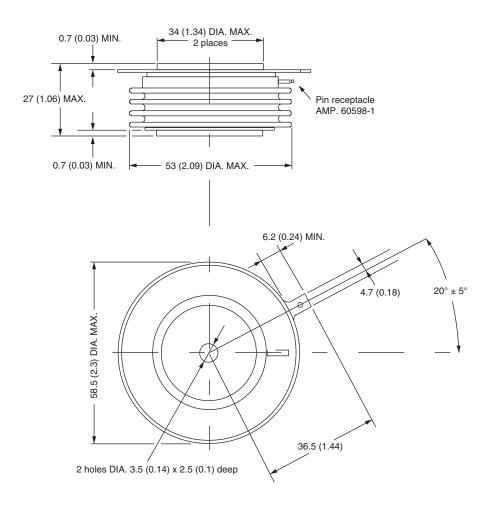
LINKS TO RELAT	ED DOCUMENTS
Dimensions	www.vishay.com/doc?95076



TO-200AC (B-PUK)

DIMENSIONS in millimeters (inches)

Creepage distance: 36.33 (1.430) minimum Strike distance: 17.43 (0.686) minimum



Quote between upper and lower pole pieces has to be considered after application of mounting force (see thermal and mechanical specification)



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